

# 74F38

## Quad 2-input NAND buffer (open collector)

Rev. 3 — 10 January 2014

Product data sheet

### 1. General description

The 74F38 provides four 2-input NAND functions with open-collector outputs.

### 2. Features and benefits

- Industrial temperature range available (–40 °C to +85 °C)

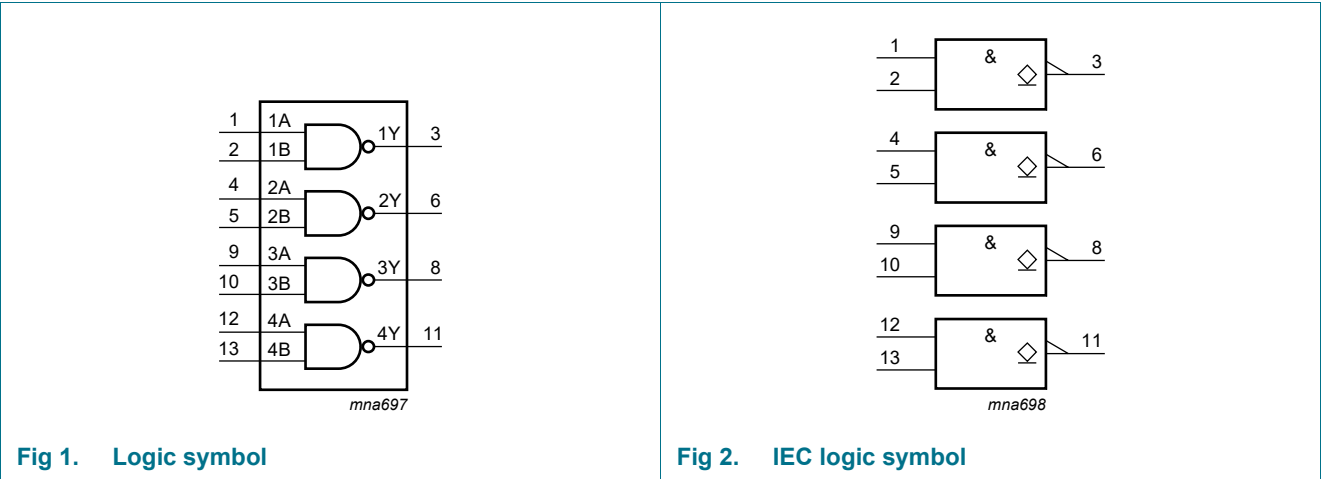
### 3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
N74F38N	0 °C to +70 °C	DIP14	plastic dual in-line package; 14 leads (300 mil)	SOT27-1
I74F38N	–40 °C to +85 °C			
N74F38D	0 °C to +70 °C	SO14	plastic small outline package; 14 leads; body width 3.9 mm	SOT108-1
I74F38D	–40 °C to +85 °C			

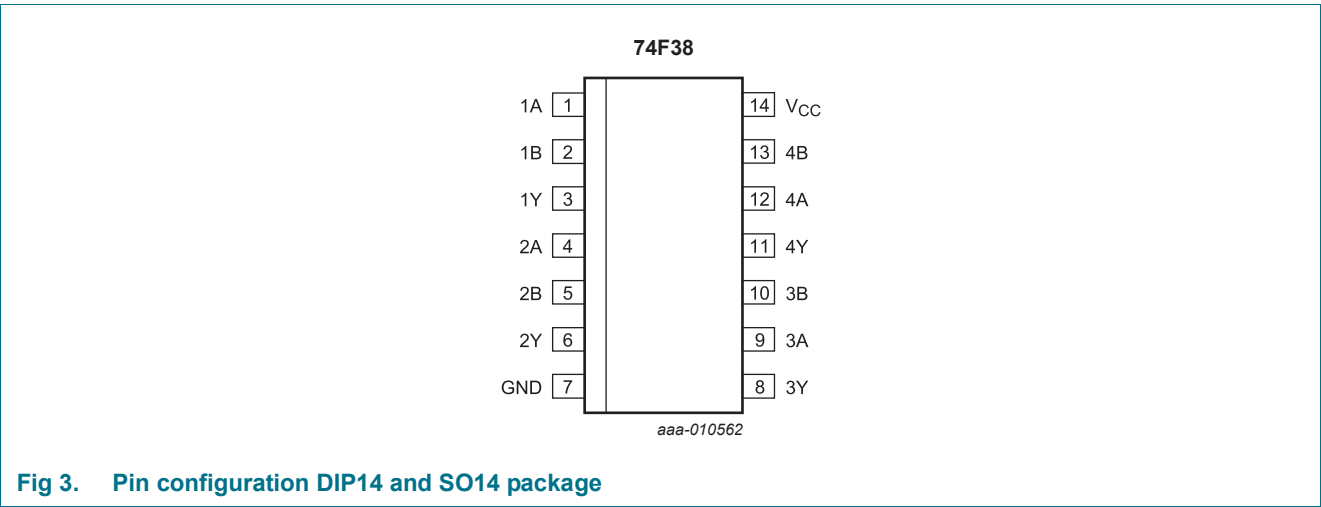


4. Functional diagram



5. Pinning information

5.1 Pinning



## 5.2 Pin description

**Table 2.** Pin description

Symbol	Pin	Description	Unit load HIGH/LOW	Load value <sup>[1][2]</sup> HIGH/LOW
1A, 2A, 3A, 4A	1, 4, 9, 12	data input	1.0/2.0	20 $\mu$ A/1.2 mA
1B, 2B, 3B, 4B	2, 5, 10, 13	data input	1.0/2.0	20 $\mu$ A/1.2 mA
1Y, 2Y, 3Y, 4Y	3, 6, 8, 11	data output	OC/106.7	OC/64 mA
GND	7	ground (0 V)	-	-
V <sub>CC</sub>	14	supply voltage	-	-

[1] One FAST Unit Load (UL) is defined as 20  $\mu$ A in HIGH state, 0.6 mA in LOW state.

[2] OC = open collector.

## 6. Functional description

**Table 3.** Function table<sup>[1]</sup>

Input		Output
nA	nB	nY
L	L	H
L	H	H
H	L	H
H	H	L

[1] H = HIGH voltage level; L = LOW voltage level; X = don't care; Z = high-impedance OFF-state.

## 7. Limiting values

**Table 4.** Limiting values

*In accordance with the Absolute Maximum Rating System (IEC 60134).*

Symbol	Parameter	Conditions	Min	Max	Unit
V <sub>CC</sub>	supply voltage		-0.5	+7.0	V
V <sub>I</sub>	input voltage		<sup>[1]</sup> -0.5	+7.0	V
V <sub>O</sub>	output voltage	output in HIGH-state	<sup>[1]</sup> -0.5	V <sub>CC</sub>	V
I <sub>IK</sub>	input clamping current	V <sub>I</sub> < 0 V	-30	+5	mA
I <sub>O</sub>	output current	output in LOW-state	-	128	mA
T <sub>amb</sub>	ambient temperature	in free-air	<sup>[2]</sup>		
		commercial	0	70	°C
		industrial	-40	+85	°C
T <sub>stg</sub>	storage temperature		-65	+150	°C

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150 °C.

## 8. Recommended operating conditions

**Table 5. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		4.5	5.0	5.5	V
$V_{IH}$	HIGH-level input voltage		2.0	-	-	V
$V_{IL}$	LOW-level input voltage		-	-	0.8	V
$V_{OH}$	HIGH-level output voltage		-	-	4.5	V
$I_{IK}$	input clamping current		-18	-	-	mA
$I_{OL}$	LOW-level output current		-	-	64	mA

## 9. Static characteristics

**Table 6. Static characteristics**

Symbol	Parameter	Conditions	25 °C			0 °C to +70 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$V_{IK}$	input clamping voltage	$V_{CC} = 4.5\text{ V}$ ; $I_{IK} = -18\text{ mA}$	-1.2	-0.73	-	-1.2	-	V
$V_{OL}$	LOW-level output voltage	$V_{CC} = 4.5\text{ V}$ ; $V_{IL} = 0.8\text{ V}$ ; $V_{IH} = 2.0\text{ V}$ $I_{OL} = 64\text{ mA}$						
		$V_{CC} = \pm 10\%$	-	-	-	-	0.55	V
		$V_{CC} = \pm 5\%$	-	0.42	-	-	0.55	V
$I_I$	input leakage current	$V_{CC} = 0\text{ V}$ ; $V_I = 7.0\text{ V}$	-	-	-	-	100	$\mu\text{A}$
$I_{IH}$	HIGH-level input current	$V_{CC} = 5.5\text{ V}$ ; $V_I = 2.7\text{ V}$	-	-	-	-	20	$\mu\text{A}$
$I_{IL}$	LOW-level input current	$V_{CC} = 5.5\text{ V}$ ; $V_I = 0.5\text{ V}$	-	-	-	-20	-	$\mu\text{A}$
$I_{CC}$	supply current	$V_{CC} = 5.5\text{ V}$						
		$V_I = \text{GND}$	-	4	-	-	7	mA
		$V_I = 4.5\text{ V}$	-	22	-	-	30	mA

[1] All typical values are measured at  $V_{CC} = 5\text{ V}$ .

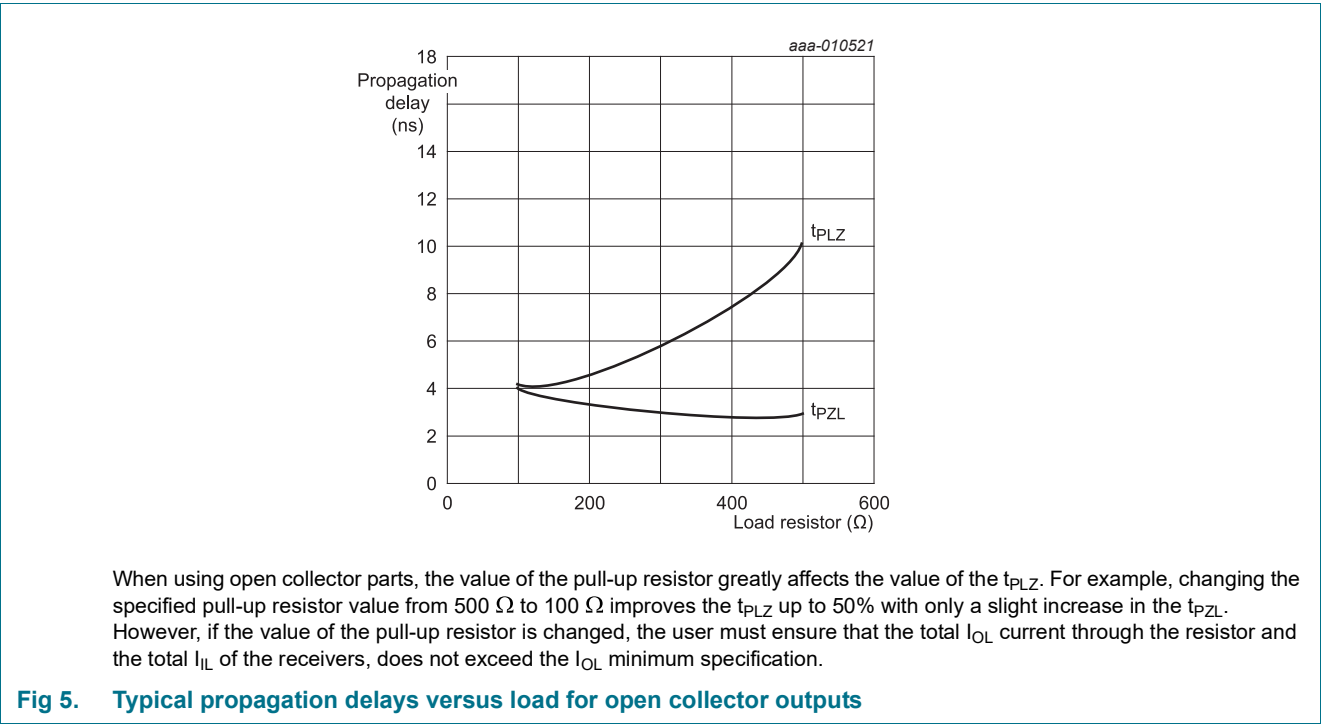
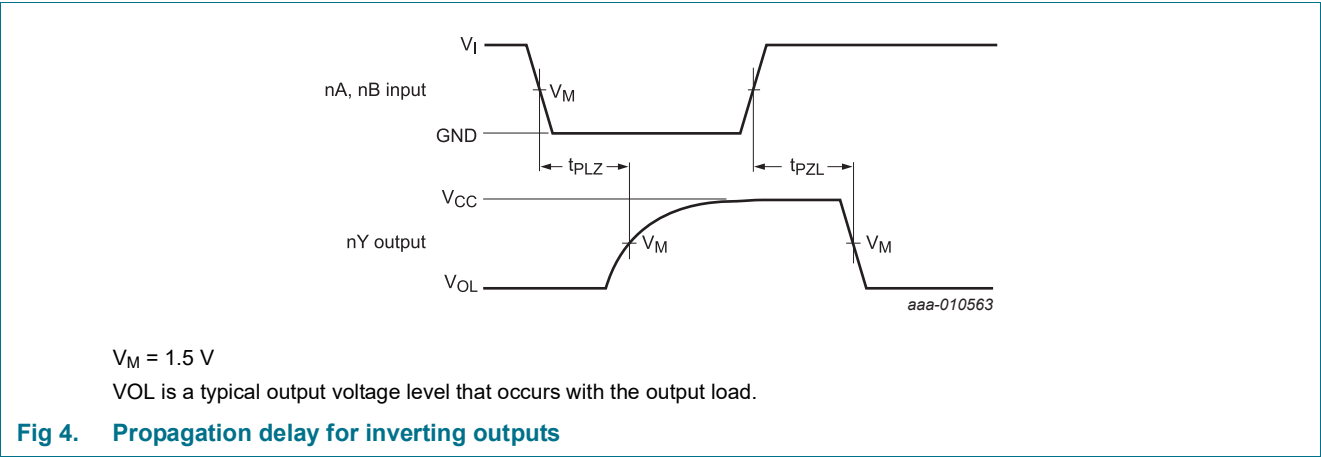
## 10. Dynamic characteristics

**Table 7. Dynamic characteristics**

$GND = 0\text{ V}$ . Test circuit is shown in [Figure 6](#).

Symbol	Parameter	Conditions	25 °C; $V_{CC} = 5.0\text{ V}$			0 °C to +70 °C; $V_{CC} = 5.0\text{ V} \pm 0.5\text{ V}$		-40 °C to +85 °C; $V_{CC} = 5.0\text{ V} \pm 0.5\text{ V}$		Unit
			Min	Typ	Max	Min	Max	Min	Max	
$t_{PZL}$	OFF-state to LOW propagation delay	nA, nB to nY; see <a href="#">Figure 4</a>	1.5	3.0	5.0	1.5	5.5	1.5	6.0	ns
$t_{PLZ}$	LOW to OFF-state propagation delay	nA, nB to nY; see <a href="#">Figure 4</a>	7.5	10.0	12.5	7.5	13.0	7.5	14.5	ns

11. Waveforms



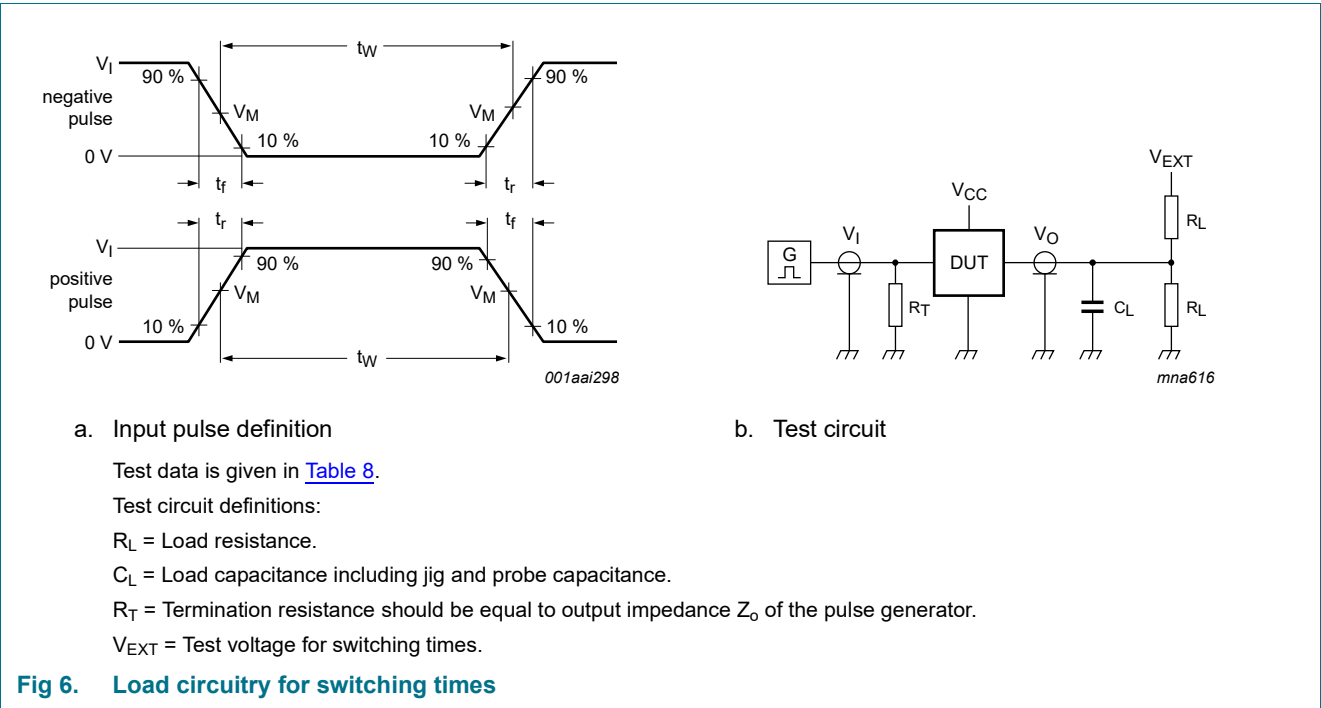


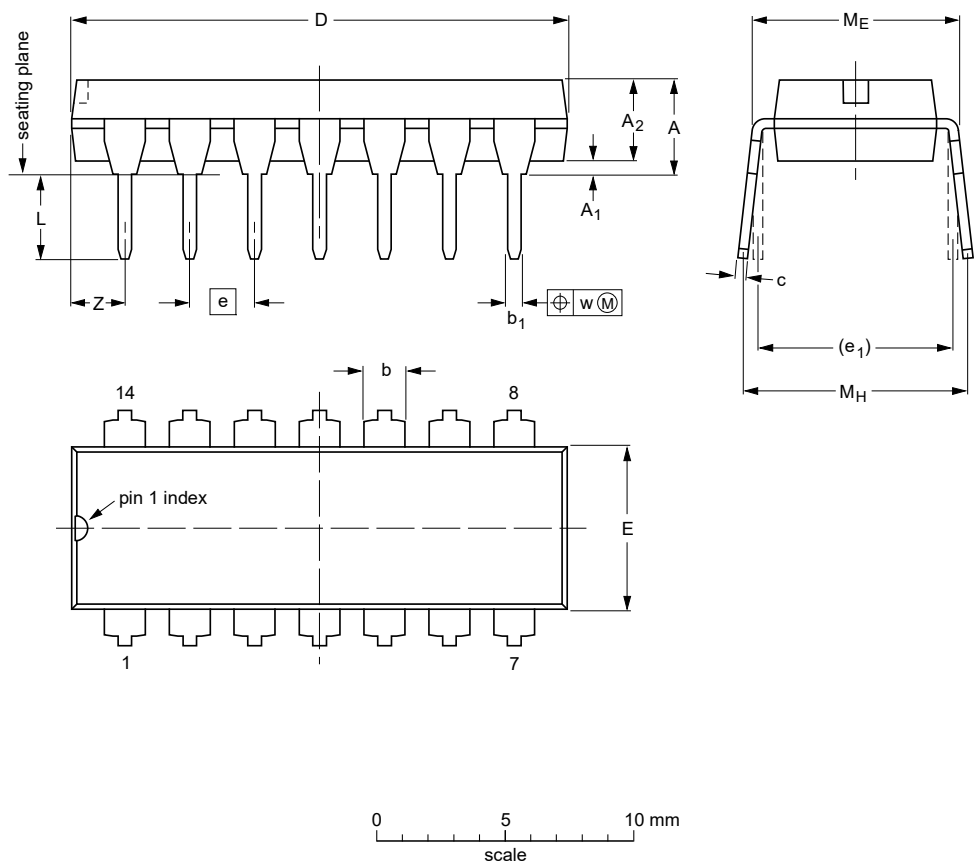
Table 8. Test data

Input				Load		$V_{EXT}$
$V_I$	$f_i$	$t_W$	$t_r, t_f$	$C_L$	$R_L$	$t_{PZL}, t_{PLZ}$
3.0 V	1 MHz	500 ns	$\leq 2.5$ ns	50 pF	500 $\Omega$	7.0 V

12. Package outline

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	c	D <sup>(1)</sup>	E <sup>(1)</sup>	e	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.02	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.1	0.3	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

**Note**  
1. Plastic or metal protrusions of 0.25 mm (0.01 inch) maximum per side are not included.


OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT27-1	050G04	MO-001	SC-501-14			99-12-27 03-02-13

Fig 7. Package outline SOT27-1 (DIP14)

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1

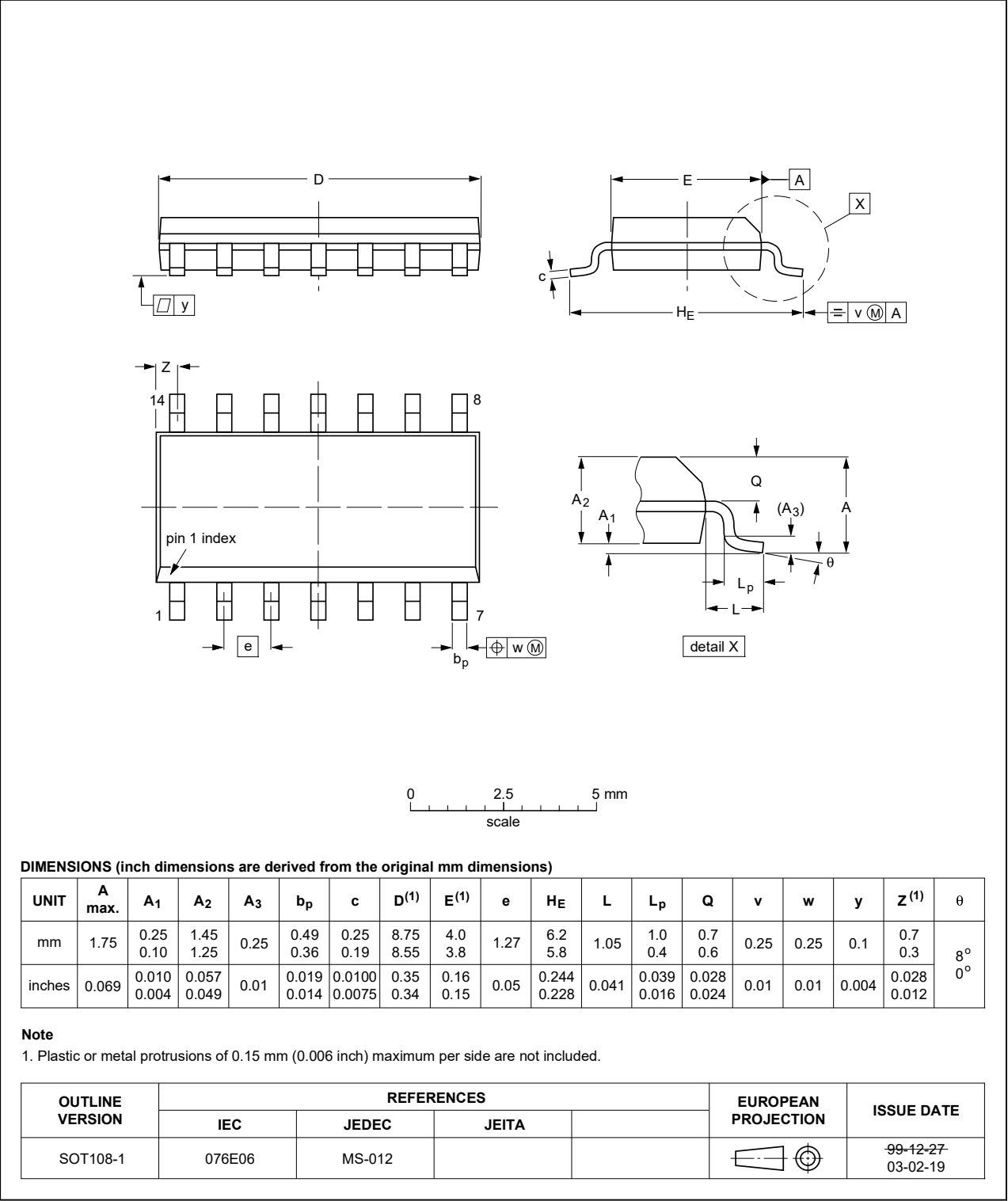


Fig 8. Package outline SOT108-1 (SO14)



## 13. Abbreviations

Table 9. Abbreviations

Acronym	Description
CDM	Charged-Device Model
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 14. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74F38 v.3	20140110	Product data sheet	-	74F38 v.2
Modifications:	<ul style="list-style-type: none"><li>• The format of this data sheet has been redesigned to comply with the new identity guidelines of NXP Semiconductors.</li><li>• Legal texts have been adapted to the new company name where appropriate.</li><li>• General update of values</li></ul>			
74F38 v.2	19901004	Product specification	-	-

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Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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## 17. Contents

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<b>1</b>	<b>General description</b> .....	<b>1</b>
<b>2</b>	<b>Features and benefits</b> .....	<b>1</b>
<b>3</b>	<b>Ordering information</b> .....	<b>1</b>
<b>4</b>	<b>Functional diagram</b> .....	<b>2</b>
<b>5</b>	<b>Pinning information</b> .....	<b>2</b>
5.1	Pinning .....	2
5.2	Pin description .....	3
<b>6</b>	<b>Functional description</b> .....	<b>3</b>
<b>7</b>	<b>Limiting values</b> .....	<b>3</b>
<b>8</b>	<b>Recommended operating conditions</b> .....	<b>4</b>
<b>9</b>	<b>Static characteristics</b> .....	<b>4</b>
<b>10</b>	<b>Dynamic characteristics</b> .....	<b>4</b>
<b>11</b>	<b>Waveforms</b> .....	<b>5</b>
<b>12</b>	<b>Package outline</b> .....	<b>7</b>
<b>13</b>	<b>Abbreviations</b> .....	<b>9</b>
<b>14</b>	<b>Revision history</b> .....	<b>9</b>
<b>15</b>	<b>Legal information</b> .....	<b>10</b>
15.1	Data sheet status .....	10
15.2	Definitions .....	10
15.3	Disclaimers .....	10
15.4	Trademarks .....	11
<b>16</b>	<b>Contact information</b> .....	<b>11</b>
<b>17</b>	<b>Contents</b> .....	<b>12</b>

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